# **Tentative**

DRAF	-124X
Total pages	page

### DRAF124X

Silicon PNP epitaxial planar type

For digital circuits

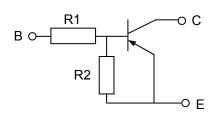
Marking Symbol: LF

Package Code: ML3-N4-B

#### Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	-50	V
Collector-emitter voltage (Base open)	VCEO	-50	V
Collector current	IC	-100	mA
Total power dissipation	PT	100	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

#### **Internal Connection**



Resistance	R1	22	kΩ
value	R2	47	kΩ
	1.	Base	
Pin name	2.	Emitte	r
	3.	Collect	tor

#### Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = -10 μA, IE = 0	-50			V
Collector-emitter voltage (Base open)	VCEO	IC = -2 mA, IB = 0	-50			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = -50 V, IE = 0			-0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = -50 V, IB = 0			-0.5	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = -6 V, IC = 0			-0.2	mA
Forward current transfer ratio	hFE	VCE = -10 V, IC = -5 mA	80		400	-
Collector-emitter saturation voltage	VCE(sat)	IC = -10  mA, IB = -0.5  mA			-0.25	V
Input voltage	Vi(on)	VCE = -0.2 V, IC = -5 mA	-2.1			\/
input voltage	Vi(off)	VCE = -5 V, IC = -100 μA			-0.6	V
Input resistance	R1		-30%	22	+30%	kΩ
Resistance ratio	R1/R2		0.37	0.47	0.57	-

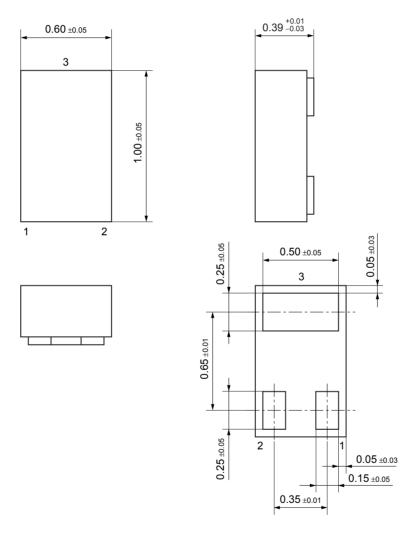
Note: Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

#### **Packing**

Embossed type (Thermo-compression sealing): 10 000 pcs / reel

2010.2.25	2010.7.12
Prepared	Revised

ML3-N4-B Unit: mm



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